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6. Carton Packaging, Packaging And Shipping Requirements • The Lid Needs To Be Fixed To The Box. • The Box Should Not Be Of A Slick Coating That Will Make The Box Hard To Handle. • All Shoes Must Face One Direction. • All Footwear Shoeboxes Are Required To Be Labeled With A UPC-A, EAN Or Interleaved 2 of 5 Labels. • Stickers Should Be Placed Feb 12th, 2024.

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10.1 LABELING AND PACKAGING: Packaging And Labeling Are ... Shampoos - Head And Shoulders, Head And Shoulders Anti Dandruff, Pantene, Pantene Damage Repair, Pantene Pro-v . SEC 4 Page 4 Of 7 In The Above Example The Following Can Be Learned About The Product Mix Of P&G Product Mix Length - 12 ... Who Is The Target Market And Who Is The Decision Maker In The Apr 11th, 2024

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